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# SPECIFICATION

## VXT144HHS-01

Preliminary Specification

Final Specification



**VICTRONIXCOMPANYLIMITED**

**CUSTOMER:**

**Made By:**

**Checked By:**

**Approved By:**

**Quality:**

**Date:**

**Note:**

**Approved By:**

**Date:**

**Note:**

**Records of Revision**

<b>DATE</b>	<b>REF.PAGE PARAGRAPH DRAWING No.</b>	<b>REVISED No.</b>	<b>SUMMARY</b>	<b>REMARK</b>
2019-04-28		V01	First Issue	

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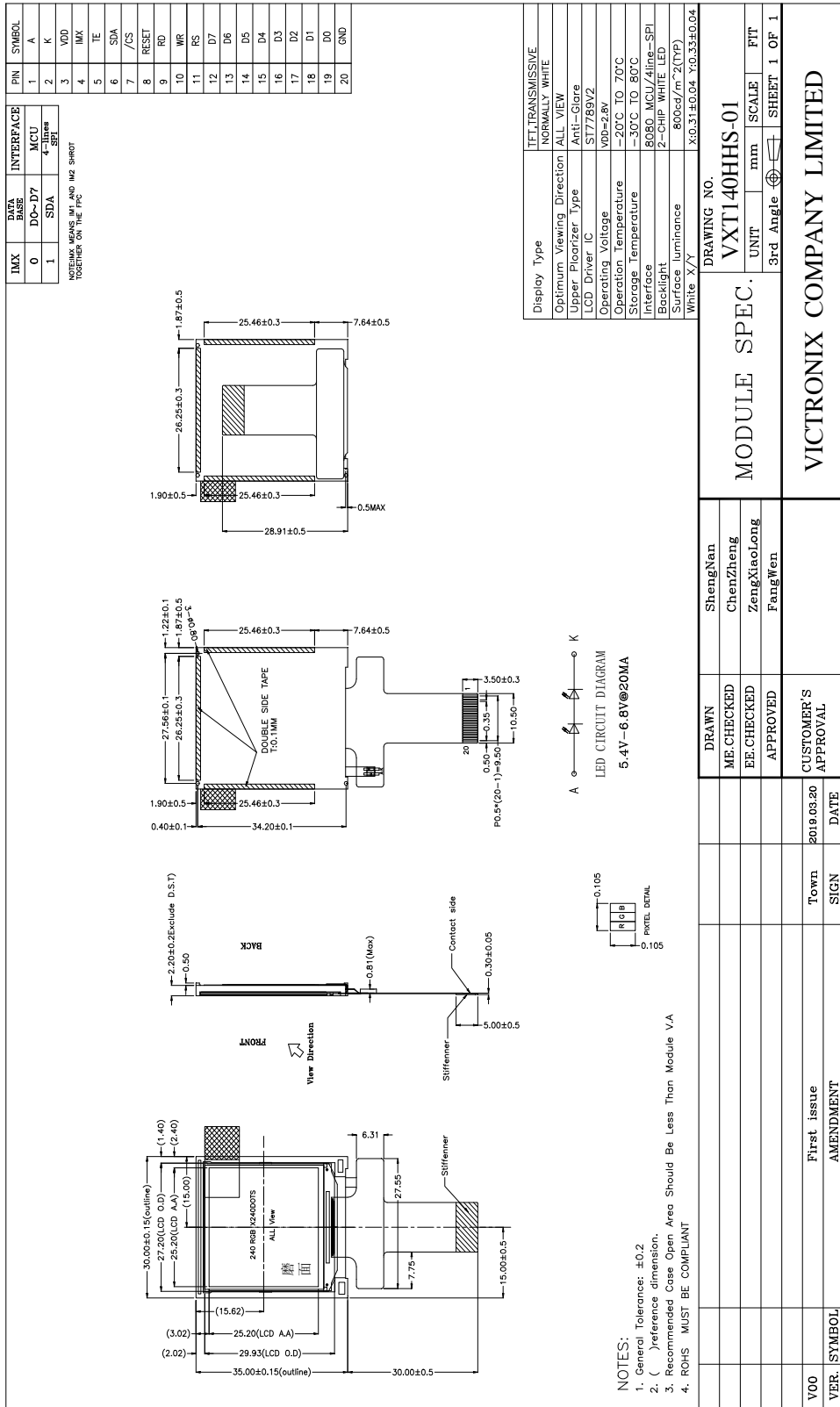
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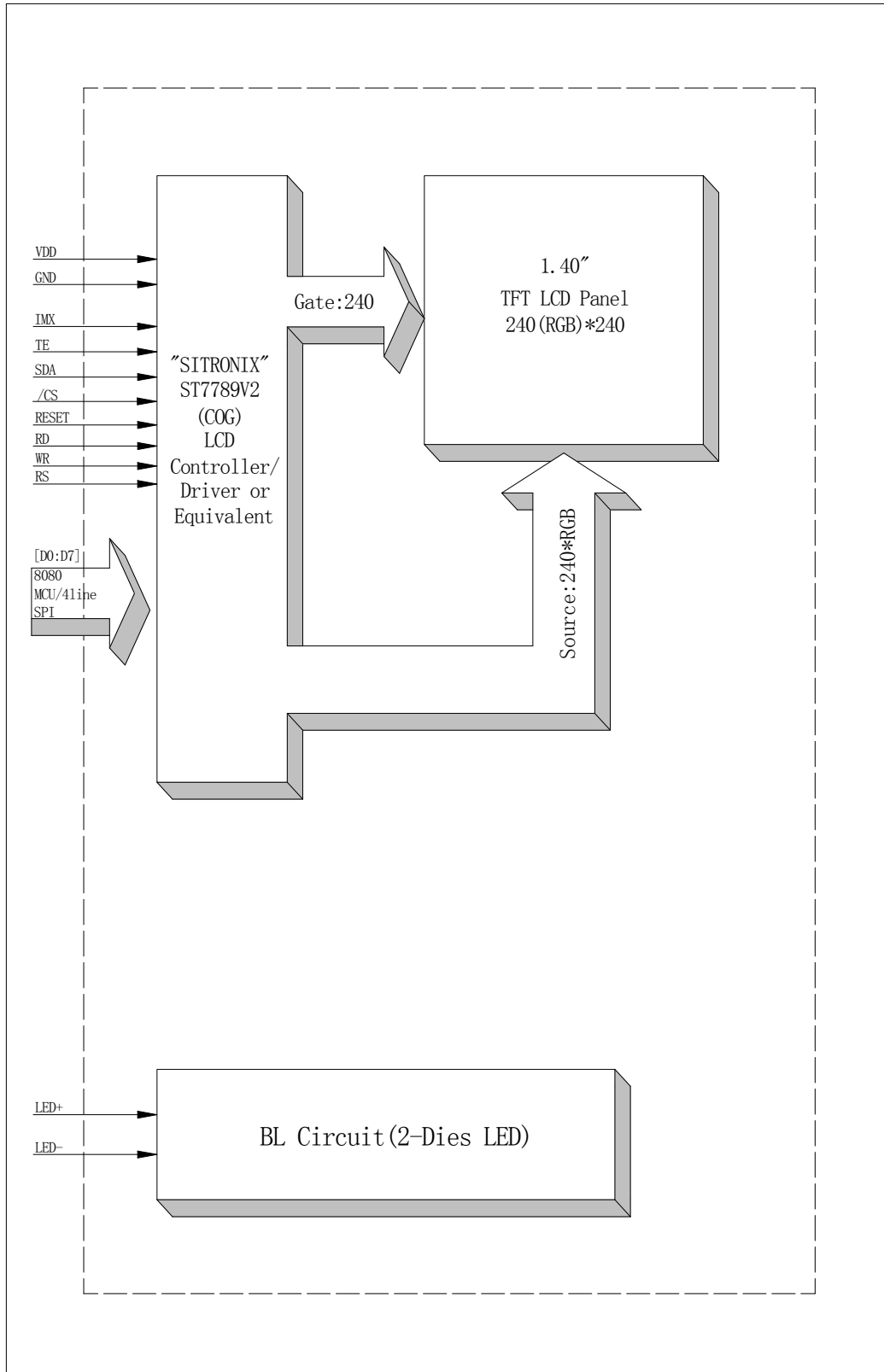
# 1. General Specification

Item	Contents	Unit
LCD TYPE	TFT/TRANSMISSIVE	
MODULE SIZE (W*H*T)	30.00*35.00*2.20	MM
ACTIVE SIZE (W*H)	25.20*25.20	MM
PIXEL PITCH (W*H)	0.105*0.105	MM
NUMBER OF DOTS	240*240	
DRIVER IC	ST7789V2	
INTERFACE TYPE	8080 MCU/4line-SPI	
TOP POLARIZER TYPE	ANTI-GLARE	
RECOMMEND VIEWING DIRECTION	ALL	O'CLOCK
GRAY SCALE INVERSION DIRECTION	-	O'CLOCK
BACKLIGHT TYPE	2-DIES WHITE LED	
TOUCH PANEL TYPE	WITHOUT	

## 2. Mechanical Drawing



### 3. Block Diagram



## 4. Interface Pin Function

Pin No.	Symbol	Description									
1	LEDA	Anode of LED backlight.									
2	LEDK	Cathode of LED backlight.									
3	VDD	Power supply									
4	IMX	<table border="1"> <thead> <tr> <th>IMX</th> <th>DATA BASE</th> <th>INTERFACE</th> </tr> </thead> <tbody> <tr> <td>0</td> <td>D0~ D7</td> <td>MCU</td> </tr> <tr> <td>1</td> <td>SDA</td> <td>4-lines SPI</td> </tr> </tbody> </table>	IMX	DATA BASE	INTERFACE	0	D0~ D7	MCU	1	SDA	4-lines SPI
		IMX	DATA BASE	INTERFACE							
		0	D0~ D7	MCU							
1	SDA	4-lines SPI									
NOTE:IMX MEANS IM1 AND IM2 SHROT TOGETHER ON THE FPC											
5	TE	Tearing effect signal is used to synchronize MCU to frame memory									
6	SDA	When IM3: Low, SPI interface input/output pin. When IM3: High, SPI interface input pin. The data is latched on the rising edge of the SCL signal. If not used, please fix this pin at VDDI or DGND level.									
7	/CS	Chip selection pin Low enable. High disable.									
8	RESET	This signal will reset the device and it must be applied to properly initialize the chip. Signal is active low.									
9	RD	Read enable in 8080 MCU parallel interface. If not used, please fix this pin at VDDI or DGND.									
10	WR	Write enable in MCU parallel interface. Display data/command selection pin in 4-line serial interface. Second Data lane in 2 data lane serial interface. If not used, please fix this pin at VDDI or DGND.									
11	RS	A register select signal. Low: select an index or status register, High: select a control register.									
12	D7	Data bus.									
13	D6	Data bus.									
14	D5	Data bus.									
15	D4	Data bus.									
16	D3	Data bus.									
17	D2	Data bus.									
18	D1	Data bus.									
19	D0	Data bus.									
20	GND	Power ground.									

## 5. Absolute Maximum Ratings

Parameter	Symbol	Min	Max	Unit
Supply voltage for analog	VDD	-0.3	4.6	V
Supply voltage for logic	VDD	-0.3	4.6	V
Supply current (One LED)	I <sub>LED</sub>		30	mA
Operating temperature	T <sub>OP</sub>	-20	+70	°C
Storage temperature	T <sub>ST</sub>	-30	+80	°C

Note : The absolute maximum rating values of this product are not allowed to be exceeded at any times. Should a module be used with any of the absolute maximum ratings exceeded, the characteristics of the module may not be recovered, or in an extreme case, the module may be permanently destroyed.



## 6. Electrical Characteristics

### 6.1 Input Power

Item	Symbol	Min	Typ.	Max	Unit	Applicable terminal
Supply Voltage for Analog	VDD	2.4	2.75	3.3	V	
Supply Voltage for Logic	VDD	2.4	2.75	3.3	V	
Input Voltage	V <sub>IL</sub>	GND	-	0.3VDD	V	
	V <sub>IH</sub>	0.7 VDD	-	VDD		
Input leakage Current	I <sub>LKG</sub>	-1		1	μA	

### 6.2 Backlight Driving Conditions

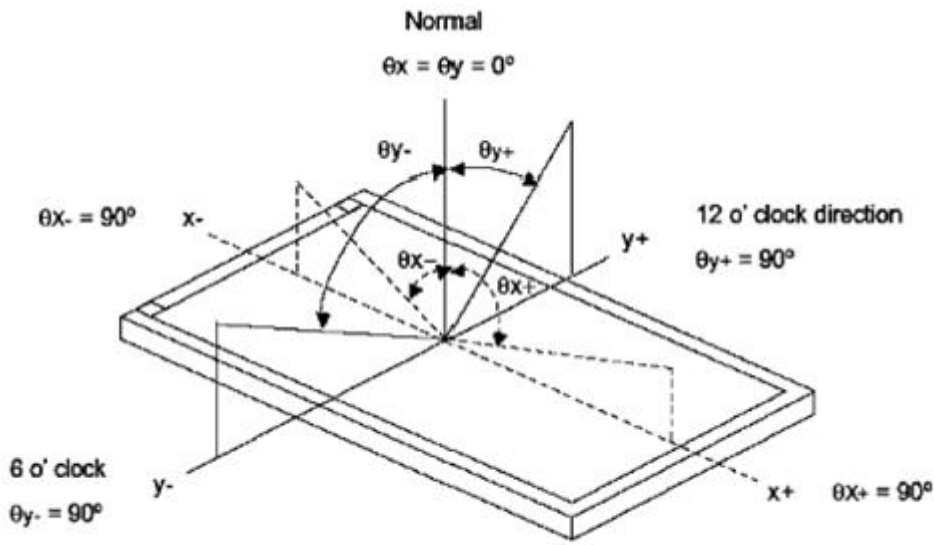
Item	Symbol	Value			Unit	Remark
		Min.	Typ.	Max.		
Voltage for LED Backlight	V <sub>F</sub>	5.4	6.4	6.8	V	I <sub>L</sub> =20mA
Current for LED Backlight	I <sub>L</sub>		20	-	mA	
Power Consumption	P		0.128		W	
LED Life Time		30,000	50,000		Hr	Note

**Note:** Brightness to be decreased to 50% of the initial value at ambient temperature TA=25°C

## 7. Optical Characteristics

ITEM	SYMBOL	CONDITIONS	SPECIFICATIONS			UNIT	NOTE
			MIN	TYP.	MAX		
Luminance	L	$I_L = 20\text{mA}$	640	800	1100	$\text{Cd/m}^2$	
Contrast Ratio	CR	$\theta = 0^\circ$	-	900	-		
Response Time	$T_{\text{ON}}$	$25^\circ\text{C}$	-	30	35	ms	
	$T_{\text{OFF}}$						
CIE Color Coordinate	Red	$X_R$	Viewing normal angle				
		$Y_R$					
	Green	$X_G$					
		$Y_G$					
	Blue	$X_B$					
		$Y_B$					
	White	$X_W$		0.270	0.310	0.350	
		$Y_W$		0.290	0.330	0.370	
Viewing Angle	Hor.	$\theta_{X+}$	$\text{CR} \geq 10$		80	Degree	
		$\theta_{X-}$			80		
	Ver.	$\theta_{Y+}$			80		
		$\theta_{Y-}$			80		
Uniformity	Un		80			%	

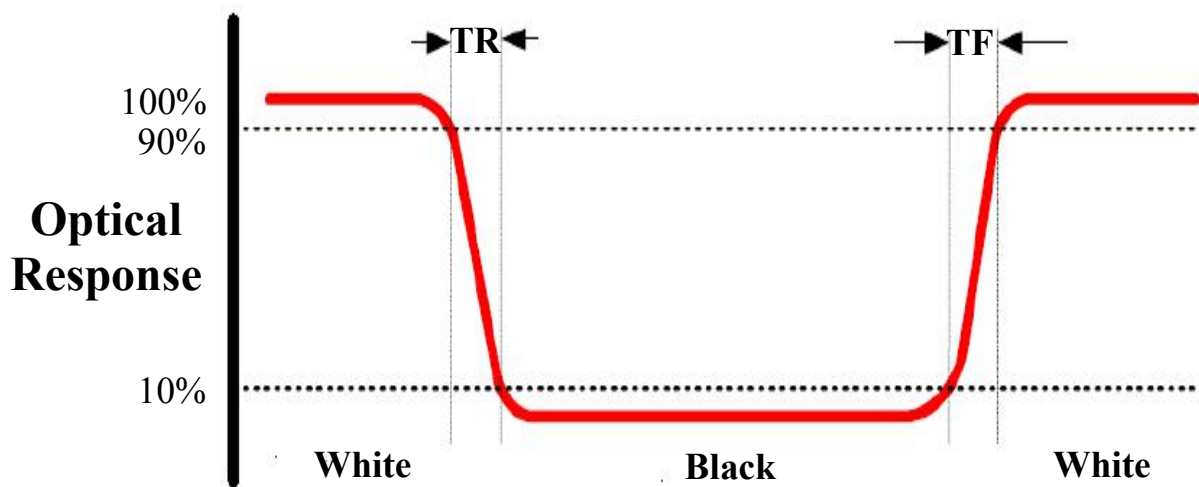
**Note 1: Definition of Viewing Angle  $\theta_x$  and  $\theta_y$ :**



**Note 2: Definition of contrast ratio CR:**

$$CR = \frac{\text{Luminance of white state}}{\text{Luminance of black state}}$$

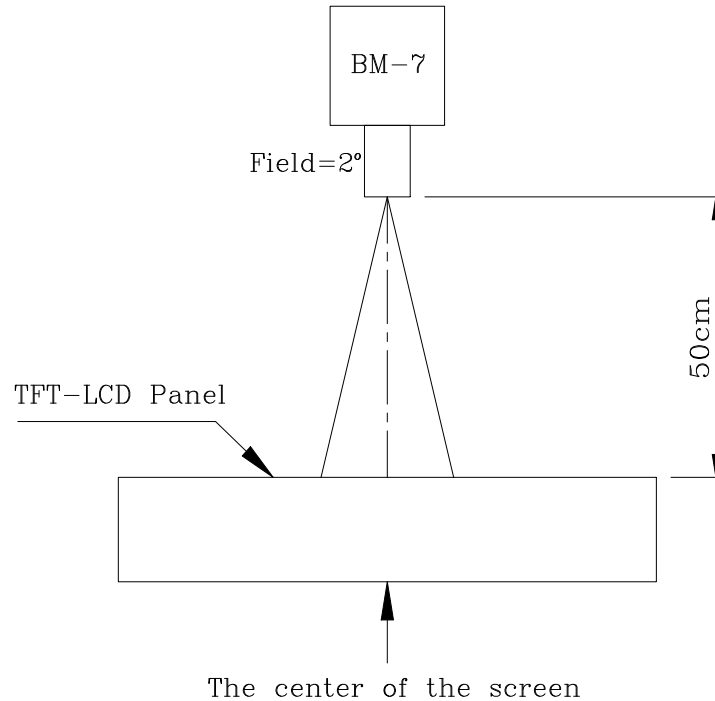
**Note 3: Definition of Response Time ( $T_r, T_f$ )**



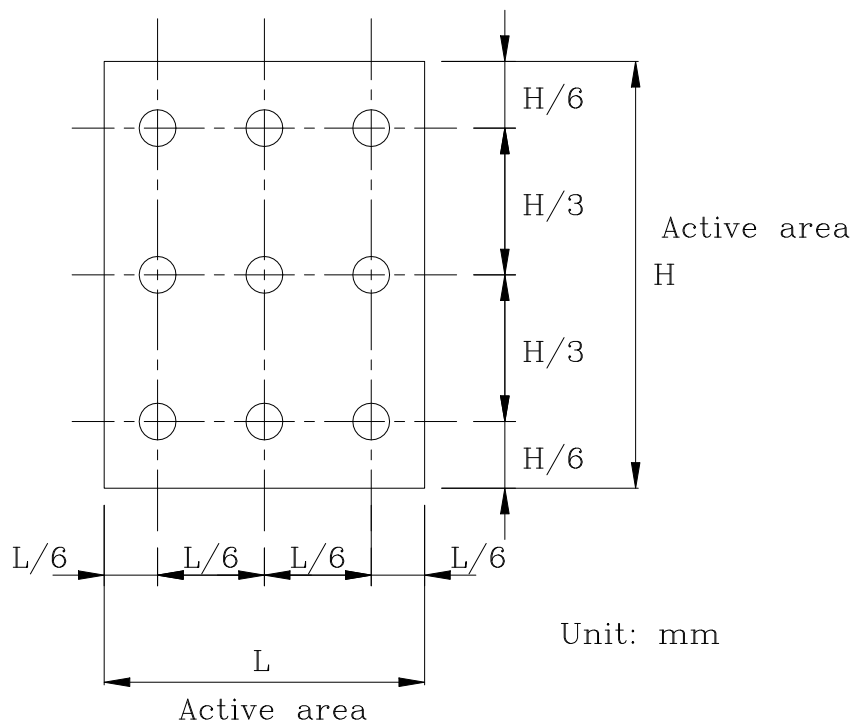
## Note 4: Definition of Luminance

### ① The Brightness Test Equipment Setup

Field=2° (As measuring “black” image, field=2° is the best testing condition)



### ② The Brightness Test Point Setup



## 8. Timing Characteristics

### 8.1 MCU Characteristics

#### 7.4.1 8080 Series MCU Parallel Interface Characteristics: 18/16/9/8-bit Bus

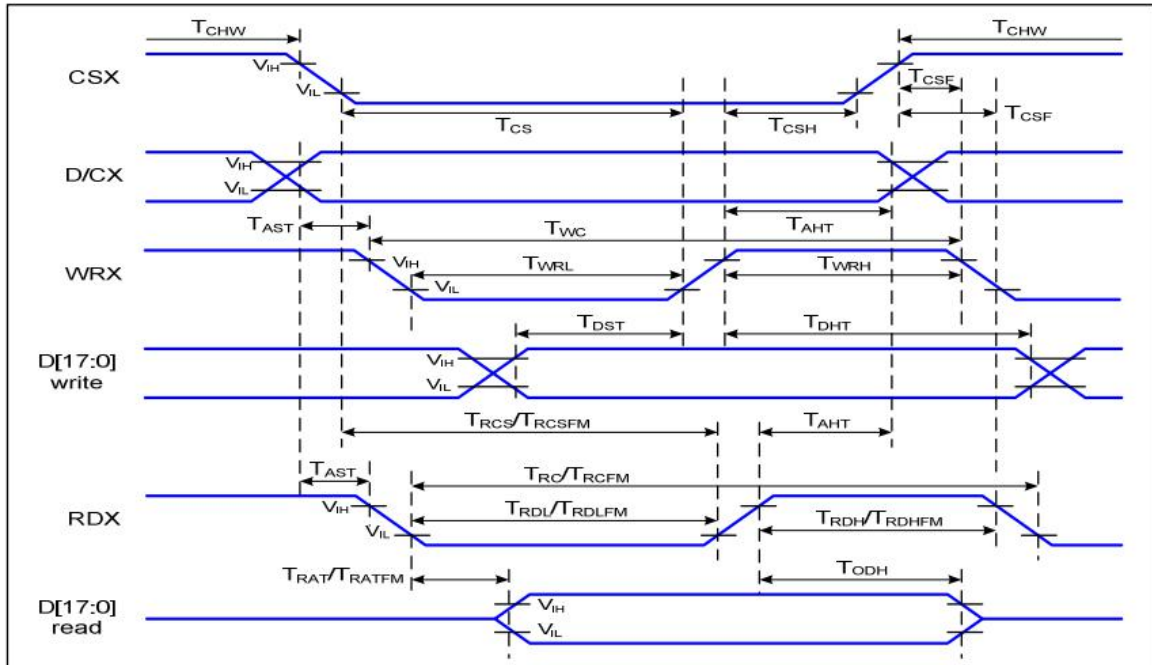


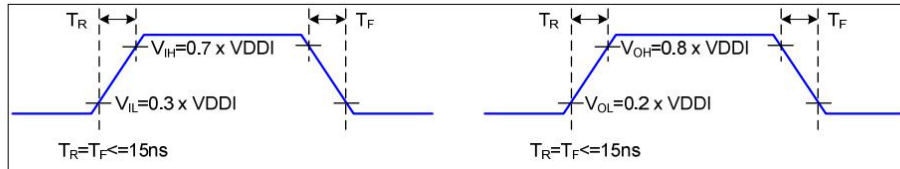
Figure 1 Parallel Interface Timing Characteristics (8080-Series MCU Interface)

VDD=1.65 to 3.3V, VDD=2.4 to 3.3V, AGND=DGND=0V, Ta=25°C

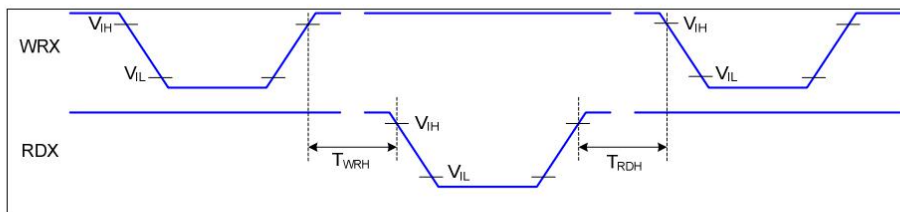
Signal	Symbol	Parameter	Min	Max	Unit	Description
D/CX	T <sub>AST</sub>	Address setup time	0		ns	-
	T <sub>AHT</sub>	Address hold time (Write/Read)	10		ns	
CSX	T <sub>CHW</sub>	Chip select "H" pulse width	0		ns	-
	T <sub>CS</sub>	Chip select setup time (Write)	15		ns	
	T <sub>RCS</sub>	Chip select setup time (Read ID)	45		ns	
	T <sub>RCSFM</sub>	Chip select setup time (Read FM)	355		ns	
	T <sub>CSF</sub>	Chip select wait time (Write/Read)	10		ns	
	T <sub>CSH</sub>	Chip select hold time	10		ns	
WRX	T <sub>WC</sub>	Write cycle	66		ns	-
	T <sub>WRH</sub>	Control pulse "H" duration	15		ns	
	T <sub>WRL</sub>	Control pulse "L" duration	15		ns	
RDX (ID)	T <sub>RC</sub>	Read cycle (ID)	160		ns	When read ID data
	T <sub>RDH</sub>	Control pulse "H" duration (ID)	90		ns	
	T <sub>RDL</sub>	Control pulse "L" duration (ID)	45		ns	
RDX (FM)	T <sub>RCFM</sub>	Read cycle (FM)	450		ns	When read from frame memory
	T <sub>RDHFM</sub>	Control pulse "H" duration (FM)	90		ns	
	T <sub>RDLFM</sub>	Control pulse "L" duration (FM)	355		ns	
D[17:0]	T <sub>DST</sub>	Data setup time	10		ns	For CL=30pF

$T_{DHT}$	Data hold time	10		ns
$T_{RAT}$	Read access time (ID)		40	ns
$T_{RATFM}$	Read access time (FM)		340	ns
$T_{ODH}$	Output disable time	20	80	ns

**Table 4 8080 Parallel Interface Characteristics**



**Figure 2 Rising and Falling Timing for I/O Signal**



**Figure 3 Write-to-Read and Read-to-Write Timing**

*Note: The rising time and falling time ( $T_r$ ,  $T_f$ ) of input signal and fall time are specified at 15 ns or less. Logic high and low levels are specified as 30% and 70% of VDDI for Input signals.*

## 8.2 4line-SPI Characteristics

### 7.4.3 Serial Interface Characteristics (4-line serial):

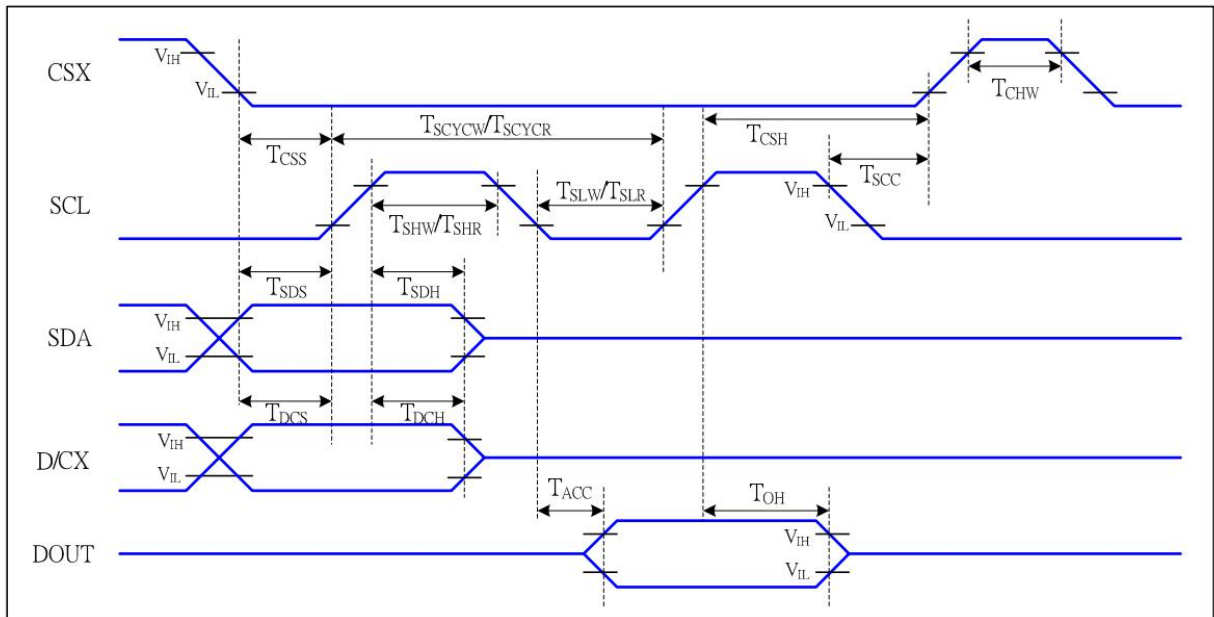


Figure 5 4-line serial Interface Timing Characteristics

VDDI=1.65 to 3.3V, VDD=2.4 to 3.3V, AGND=DGND=0V, Ta=25°C

Signal	Symbol	Parameter	MIN	MAX	Unit	Description
CSX	T <sub>CSS</sub>	Chip select setup time (write)	15		ns	
	T <sub>CSH</sub>	Chip select hold time (write)	15		ns	
	T <sub>CSS</sub>	Chip select setup time (read)	60		ns	
	T <sub>SCC</sub>	Chip select hold time (read)	65		ns	
	T <sub>CHW</sub>	Chip select "H" pulse width	40		ns	
SCL	T <sub>SCYCW</sub>	Serial clock cycle (Write)	16		ns	-write command & data ram
	T <sub>SHW</sub>	SCL "H" pulse width (Write)	7		ns	
	T <sub>SLW</sub>	SCL "L" pulse width (Write)	7		ns	
	T <sub>SCYCR</sub>	Serial clock cycle (Read)	150		ns	-read command & data ram
	T <sub>SHR</sub>	SCL "H" pulse width (Read)	60		ns	
	T <sub>SLR</sub>	SCL "L" pulse width (Read)	60		ns	
D/CX	T <sub>DCS</sub>	D/CX setup time	10		ns	
	T <sub>DCH</sub>	D/CX hold time	10		ns	
SDA (DIN)	T <sub>SDS</sub>	Data setup time	7		ns	
	T <sub>SDH</sub>	Data hold time	7		ns	
DOUT	T <sub>ACC</sub>	Access time	10	50	ns	For maximum CL=30pF
	T <sub>OH</sub>	Output disable time	15	50	ns	For minimum CL=8pF

Table 6 4-line serial Interface Characteristics

## 9. Standard Specification for Reliability

### 9.1 Standard Specification for Reliability of LCD Module

No	Test Item	Condition	Remarks
1	High Temperature Operation	Ts = +70°C, 240 hours	IEC60068-21:2007 GB2423.2-2008
2	Low Temperature Operation	Ta = -20°C, 240 hours	IEC60068-2-1:2007 GB/2423.1-2008
3	High Temperature Storage	Ta = +80°C, 240 hours	IEC60068-21:2007 GB/2423.2-2008
4	Low Temperature Storage	Ta = -30°C, 240 hours	IEC60068-21:2007 GB/2423.1-2008
5	Storage at High Temperature and Humidity	Ta = +60°C, 90% RH max,240hours	IEC60068-2-78 :2001 GB/T2423.3—2006
6	Thermal Shock (non-operation)	-30°C 30 min~+80°C 30 min, Change time:5min, 20 Cycle	Start with cold temperature, End with high temperature, IEC60068-214:1984, GB/2423.22-2002
7	ESD	C=150pF,R=330Ω,5point/panel Air:±8Kv,5times; Contact:±4Kv,5times (Environment:15°C~35°C, 30%~60%.86Kpa~106Kpa)	IEC61000-42:2001 GB/T17626.2-2006
8	Vibration Test	Frequency range:10~55Hz Stroke:1.5mm Sweep:10Hz~55Hz~10Hz 2 hours for each direction of X.Y.Z (6 hours for total)	IEC60068-2-6:1982 GB/T2423.101995
9	Mechanical Shock (Non Op)	Half Sine Wave60G 6ms, ±X,±Y,±Z 3times for each direction	IEC60068-2-27:1987 GB/T2423.5—1995
10	Package Drop Test	Height:80cm, 1corner,3 edges,6 surfaces	IEC60068-2-32:1990 GB/T2423.8—1995

Note1: Ts is the temperature of panel's surface.

Note2: Ta is the ambient temperature of sample.



## 9.2 Testing Conditions and Inspection Criteria

For the final test, the testing sample must be stored at room temperature for 24 hours. After the tests listed in Table 9.2, standard specifications for reliability will be executed in order to ensure stability.

<b>No.</b>	<b>Item</b>	<b>Test Model</b>	<b>In section Criteria</b>
01	Current Consumption	Refer To Specification	The current consumption should conform to the product specification.
02	Contrast	Refer To Specification	After the tests have been executed, the contrast must be larger than half of its initial value prior to the tests.
03	Appearance	Visual inspection	Defect free.

## 9.3 MTBF

MTBF	Functions, performance, appearance, etc. shall be free from remarkable deterioration within 50,000 hours under ordinary operating and storage conditions room temperature ( $25\pm 5^{\circ}\text{C}$ ), normal humidity ( $50\pm 10\%$ RH), and in area not exposed to direct sun light.
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# 10. Specification of Quality Assurance

This standard of Quality Assurance confirms to the quality of LCD module products supplied by Victronix.

## 10.1 Quality Test

Before delivering, the supplier should conduct the following tests to confirm the quality of products.

- Electrical-Optical Characteristics: According to the individual specification to test the product.
- Appearance Characteristics: According to the individual specification to test the product.
- Reliability Characteristics: According to the definition of reliability on the specification for testing products.

## 10.2 Delivery Test

Before delivering, the supplier should conduct the delivery test.

- Test method: According to MIL-STD105E.General Inspection Level II take a single Time.
- The defects classify of AQL as following:  
Major defect: AQL = 0.65  
Minor defect: AQL = 1.5  
Total defects: AQL = 1.5

## 10.3 Non-conforming Analysis & Deal With Manners

### 10.3.1 Non-conforming Analysis

- Purchaser should provide the data detail of non-conforming sample and the non-conforming.
- After receiving the data detail from purchaser, the analysis of non-conforming should be finished within two weeks.
- If the analysis can't be finished on time, supplier must notice purchaser 3 days in advance.

### 10.3.2 Disposition of non-conforming

- If any product defect be found during assembling, supplier must change the good for every defect after confirmation.
- Both supplier and customer should analyze the reason and discuss the disposition of non-conforming when the reason of nonconforming is not sure.

## 10.4 Agreement items

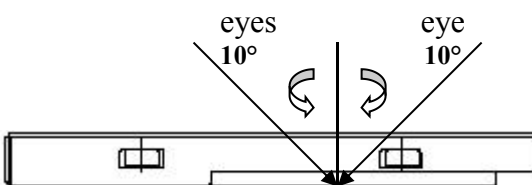
Both parties should negotiate together when the following problems happen.

- There is any problem of standard of quality assurance, and both sides should agree that it must be modified.
- There is any argument item which does not record in the standard of quality assurance.
- Any other special problem.

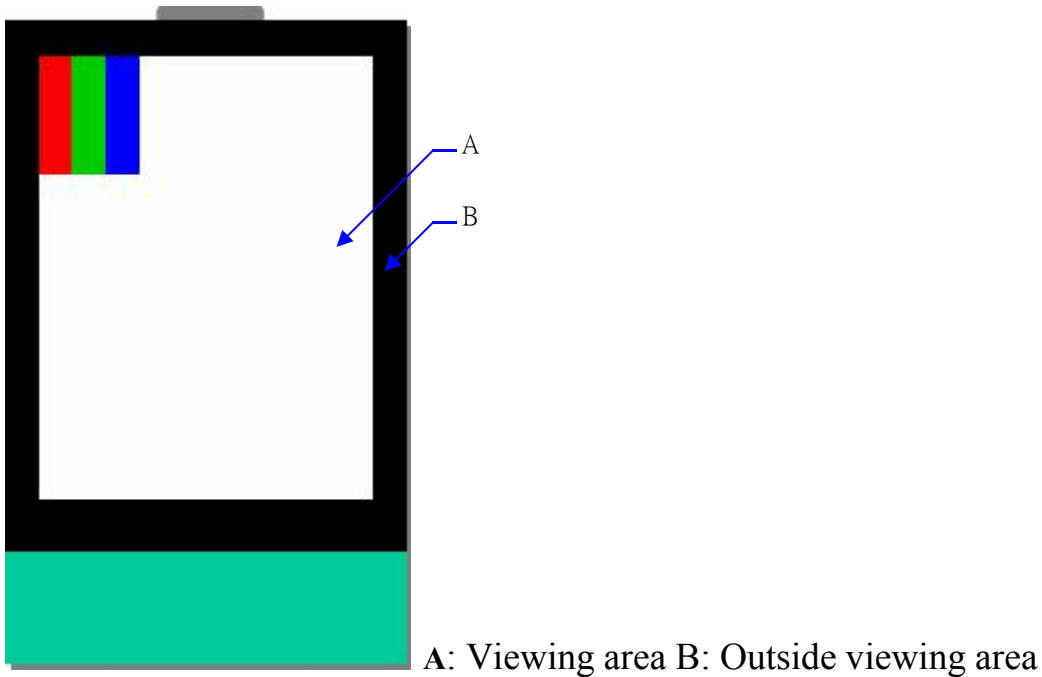
## 10.5 Standard of The Product Appearance Test

### 10.5.1 Manner of appearance test

- The test must be under 20W × 2 or 40W fluorescent light, and the distance of view must be at 30±5cm.
- When test the model of transmissive product must add the reflective plate.
- The test direction is base on around 10° of vertical line.
- Temperature: 25±5°C Humidity: 60±10%RH



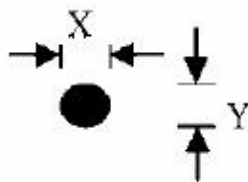
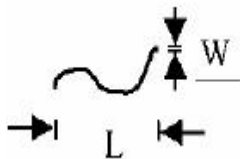
- Definition of area:

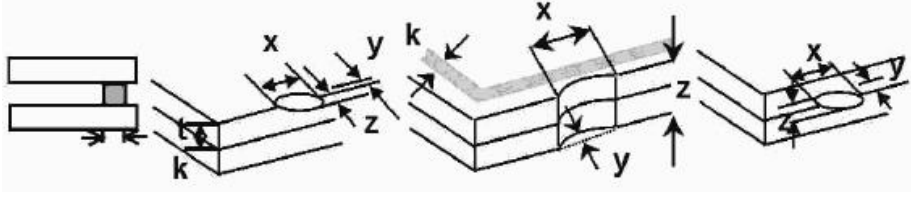
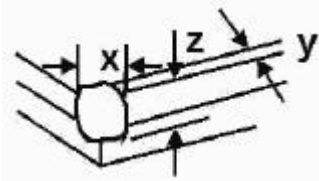


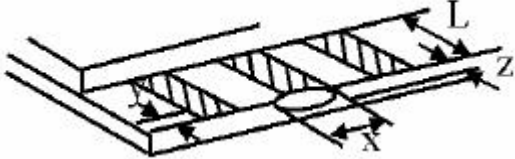
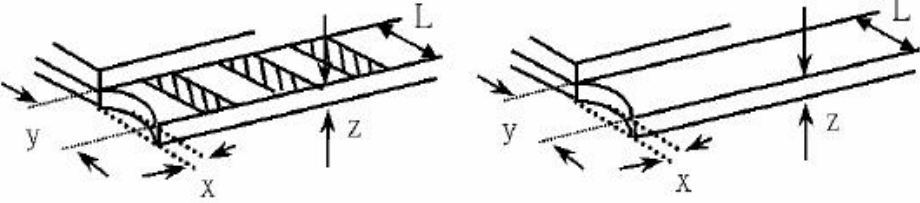
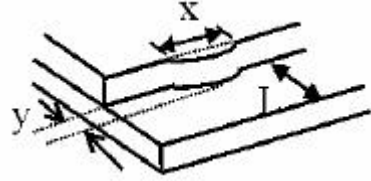
## 10.5.2 Basic principle

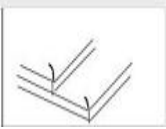
- When the standard can not be described, AQL will be applied.
- The sample of the lowest acceptable quality level must be negotiated by both supplier and customer when any dispute happened.
- New item must be added on time when it is necessary.

## 10.6 Inspection Specification

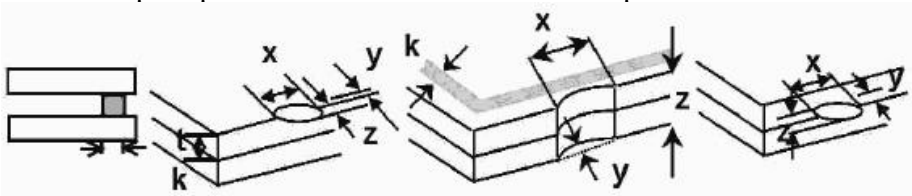
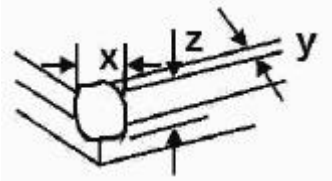
NO.	Item	Criterion	AQL												
01	Electrical Testing	1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character, dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 LCD viewing angle defect. 1.7 Mixed product types. 1.8 Flicker	0.65												
02	Black or White spots or Bright spots or Color spots on LCD (Display only)	2.1 White and black or color spots on display $\leq 0.25\text{mm}$ , no more than Five spots. 2.2 Densely spaced: No more than three spots within 3mm.	1.5												
03	LCD and Touch Panel black spots, white spots, contamination (non – display)	3.1 Round type: As following drawing $\Phi = (X+Y) / 2$  <table border="1" data-bbox="821 1086 1348 1332"> <thead> <tr> <th>Size(mm)</th> <th>Acceptable Q'ty</th> </tr> </thead> <tbody> <tr> <td><math>\Phi \leq 0.10</math></td> <td>Accept no dense</td> </tr> <tr> <td><math>0.10 &lt; \Phi \leq 0.20</math></td> <td>2</td> </tr> <tr> <td><math>0.20 &lt; \Phi \leq 0.25</math></td> <td>2</td> </tr> <tr> <td><math>0.25 &lt; \Phi \leq 0.30</math></td> <td>1</td> </tr> <tr> <td><math>0.30 &lt; \Phi</math></td> <td>0</td> </tr> </tbody> </table> <p>* Densely spaced: No more than two spots within 3mm.</p>	Size(mm)	Acceptable Q'ty	$\Phi \leq 0.10$	Accept no dense	$0.10 < \Phi \leq 0.20$	2	$0.20 < \Phi \leq 0.25$	2	$0.25 < \Phi \leq 0.30$	1	$0.30 < \Phi$	0	1.5
		Size(mm)	Acceptable Q'ty												
$\Phi \leq 0.10$	Accept no dense														
$0.10 < \Phi \leq 0.20$	2														
$0.20 < \Phi \leq 0.25$	2														
$0.25 < \Phi \leq 0.30$	1														
$0.30 < \Phi$	0														
3.2 Line type: (As following drawing)  <table border="1" data-bbox="726 1489 1348 1758"> <thead> <tr> <th>Length(mm)</th> <th>Width(mm)</th> <th>Acceptable Q'ty</th> </tr> </thead> <tbody> <tr> <td>---</td> <td><math>W \leq 0.02</math></td> <td>Accept no dense</td> </tr> <tr> <td><math>L \leq 3.0</math></td> <td><math>0.02 &lt; W \leq 0.05</math></td> <td rowspan="2">2</td> </tr> <tr> <td><math>L \leq 2.5</math></td> <td><math>0.03 &lt; W \leq 0.08</math></td> </tr> <tr> <td>---</td> <td><math>0.08 &lt; W</math></td> <td>Rejection</td> </tr> </tbody> </table> <p>* Densely spaced: No more than two lines within 3mm.</p>	Length(mm)	Width(mm)	Acceptable Q'ty	---	$W \leq 0.02$	Accept no dense	$L \leq 3.0$	$0.02 < W \leq 0.05$	2	$L \leq 2.5$	$0.03 < W \leq 0.08$	---	$0.08 < W$	Rejection	1.5
Length(mm)	Width(mm)	Acceptable Q'ty													
---	$W \leq 0.02$	Accept no dense													
$L \leq 3.0$	$0.02 < W \leq 0.05$	2													
$L \leq 2.5$	$0.03 < W \leq 0.08$														
---	$0.08 < W$	Rejection													

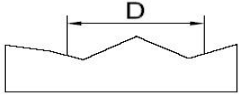
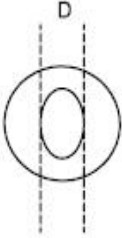
NO.	Item	Criterion		AQL	
04	Polarizer bubbles	If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction	Size $\Phi$ (mm)	Acceptable Q'ty	1.5
			$\Phi \leq 0.20$	Accept no dense	
			$0.20 < \Phi \leq 0.50$	3	
			$0.50 < \Phi \leq 1.00$	2	
			Total Q'ty	3	
05	Scratches	Follow NO.3 -2 Line Type.			
06	Chipped glass	Symbols: x: Chip length    y: Chip width    z: Chip thickness k: Seal width    t: Glass thickness    a: LCD side length L: Electrode pad length 6.1 General glass chip: 6.1.1 Chip on panel surface and crack between panels:		1.5	
					
		z: Chip thickness	y: Chip width		x: Chip length
		$Z \leq 1/2t$	Not over viewing area		$x \leq 1/8a$
		$1/2t < z \leq 2t$	Not exceed 1/3k		$x \leq 1/8a$
⊙ Unit: mm ⊙ If there are 2 or more chips, x is the total length of each chip 6.1.2 Corner crack:					
					
z: Chip thickness	y: Chip width		x: Chip length		
$Z \leq 1/2t$	Not over viewing area		$x \leq 1/8a$		
$1/2t < z \leq 2t$	Not exceed 1/3k		$x \leq 1/8a$		
⊙ Unit: mm ⊙ If there are 2 or more chips, x is the total length of each chip					

NO.	Item	Criterion	AQL																
07	Glass crack	<p>Symbols:            x: Chip length    y: Chip width    z: Chip thickness            k: Seal width    t: Glass thickness    a: LCD side length            L: Electrode pad length</p> <p>7.2 Protrusion over terminal:            7.2.1 Chip on electrode pad:</p>  <table border="1" data-bbox="560 757 1236 902"> <tr> <td>y: Chip width</td> <td>x: Chip length</td> <td>z: Chip thickness</td> </tr> <tr> <td><math>y \leq 0.5\text{mm}</math></td> <td><math>x \leq 1/8a</math></td> <td><math>0 &lt; z \leq t</math></td> </tr> </table> <p>7.2.2            Non-conductive portion:</p>  <table border="1" data-bbox="560 1272 1236 1417"> <tr> <td>y: Chip width</td> <td>x: Chip length</td> <td>z: Chip thickness</td> </tr> <tr> <td><math>y \leq L</math></td> <td><math>x \leq 1/8a</math></td> <td><math>0 &lt; z \leq t</math></td> </tr> </table> <p>⊙ If there chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications.            ⊙ If the product will be heat sealed by the customer, the alignment mark must not be damaged.</p> <p>7.2.3 Substrate protuberance and internal crack</p>  <table border="1" data-bbox="890 1742 1326 1888"> <tr> <td>y: width</td> <td>x: length</td> </tr> <tr> <td><math>y \leq 1/3L</math></td> <td><math>X \leq a</math></td> </tr> </table>	y: Chip width	x: Chip length	z: Chip thickness	$y \leq 0.5\text{mm}$	$x \leq 1/8a$	$0 < z \leq t$	y: Chip width	x: Chip length	z: Chip thickness	$y \leq L$	$x \leq 1/8a$	$0 < z \leq t$	y: width	x: length	$y \leq 1/3L$	$X \leq a$	1.5
y: Chip width	x: Chip length	z: Chip thickness																	
$y \leq 0.5\text{mm}$	$x \leq 1/8a$	$0 < z \leq t$																	
y: Chip width	x: Chip length	z: Chip thickness																	
$y \leq L$	$x \leq 1/8a$	$0 < z \leq t$																	
y: width	x: length																		
$y \leq 1/3L$	$X \leq a$																		

NO.	Item	Criterion	AQL
08	Cracked glass	The LCD with any extensive crack is not acceptable. 	1.5
09	Backlight elements	9.1 Illumination source flickers when lit. 9.2 Spots or scratches that appear when lit must be judged. Using LCD spot, lines and contamination standards. 9.3 Backlight doesn't light or color is wrong.	1.5 1.5 0.65
10	Bezel	Bezel must comply with product specifications.	1.5
11	PCB、COB	11.1 COB seal may not have pinholes larger than 0.2mm or contamination. 11.2 COB seal surface may not have pinholes through to the IC. 11.3 The height of the COB should not exceed the height indicated in the assembly diagram. 11.4 There may not be more than 2mm of sealant outside the seal area on PCB. And there should be no more than three places. 11.5 Parts on PCB must be the same as on the production characteristic chart, There should be no wrong parts, missing parts or excess parts. 11.6 The jumper on the PCB should conform to the product characteristic chart.	1.5 1.5 1.5 1.5 0.65 0.65
12	FPC	12.1 FPC terminal damage $\cong$ 1/2 FPC terminal width and can not affect the function , we judge accept. 12.2 FPC alignment hole damage $\cong$ 1/2 alignment area and can not affect the function , we judge accept.	1.5 1.5
13	Soldering	13.1 No cold solder joints, missing solder connections, oxidation or icicle. 13.2 No short circuits in components on PCB or FPC.	1.5 0.65



NO.	Item	Criterion	AQL												
14	Touch Panel Chipped glass	<p>Symbols:            x: Chip length    y: Chip width    z: Chip thickness            k: Seal width    t: Touch Panel Total thickness    a: LCD side length            L: Electrode pad length</p> <p>14.1 General glass chip:            14.1.1 Chip on panel surface and crack between panels:</p>  <table border="1" data-bbox="451 763 1270 981"> <tr> <td>z: Chip thickness</td> <td>y: Chip width</td> <td>x: Chip length</td> </tr> <tr> <td><math>Z \leq t</math></td> <td><math>\cong 1/2 k</math> and not over viewing area</td> <td><math>x \leq 1/8a</math></td> </tr> </table> <p>⊙ Unit: mm            ⊙ If there are 2 or more chips, x is the total length of each chip</p> <p>14.1.2 Corner crack:</p>  <table border="1" data-bbox="451 1357 1270 1574"> <tr> <td>z: Chip thickness</td> <td>y: Chip width</td> <td>x: Chip length</td> </tr> <tr> <td><math>z \leq t</math></td> <td><math>\cong 1/2 k</math> and not over viewing area</td> <td><math>x \leq 1/8a</math></td> </tr> </table> <p>⊙ Unit: mm            ⊙ If there are 2 or more chips, x is the total length of each chip</p>	z: Chip thickness	y: Chip width	x: Chip length	$Z \leq t$	$\cong 1/2 k$ and not over viewing area	$x \leq 1/8a$	z: Chip thickness	y: Chip width	x: Chip length	$z \leq t$	$\cong 1/2 k$ and not over viewing area	$x \leq 1/8a$	1.5
z: Chip thickness	y: Chip width	x: Chip length													
$Z \leq t$	$\cong 1/2 k$ and not over viewing area	$x \leq 1/8a$													
z: Chip thickness	y: Chip width	x: Chip length													
$z \leq t$	$\cong 1/2 k$ and not over viewing area	$x \leq 1/8a$													

NO.	Item	Criterion	AQL										
15	Touch Panel(Fish eye、dent and bubble on film)	<table border="1"> <thead> <tr> <th>SIZE(mm)</th> <th>Acceptable Q'ty</th> </tr> </thead> <tbody> <tr> <td><math>\Phi \leq 0.2</math></td> <td>Accept no dense</td> </tr> <tr> <td><math>0.2 &lt; D \leq 0.4</math></td> <td>5</td> </tr> <tr> <td><math>0.4 &lt; D \leq 0.5</math></td> <td>2</td> </tr> <tr> <td><math>0.5 &lt; D</math></td> <td>0</td> </tr> </tbody> </table>  	SIZE(mm)	Acceptable Q'ty	$\Phi \leq 0.2$	Accept no dense	$0.2 < D \leq 0.4$	5	$0.4 < D \leq 0.5$	2	$0.5 < D$	0	1.5
SIZE(mm)	Acceptable Q'ty												
$\Phi \leq 0.2$	Accept no dense												
$0.2 < D \leq 0.4$	5												
$0.4 < D \leq 0.5$	2												
$0.5 < D$	0												
16	Touch Panel Newton ring	Newton ring dimension $\leq 1/2$ touch panel area and not affect font and line distortion( $\leq 2.5\%$ ) , it is acceptable.	1.5										
17	Touch Panel Linearity	Less than 2.5% is acceptable.	1.5										
18	LCD Ripple	Touch the touch panel , can not see the LCD ripple. Pen: R 1.0mm silicon rubber. Operation Force: 80g	1.5										
19	General appearance	19.1 Pin type must match type in specification sheet. 19.2 LCD pin loose or missing pins. 19.3 Product packaging must the same as specified on packaging specification sheet. 19.4 Product dimension and structure must conform to product specification sheet.	0.65 0.65 0.65 0.65										

## 11. Handling Precaution

### 11.1 Handling of LCM

- Avoid external shock.
- Don't apply excessive force on the surface.
- Liquid in LCD is hazardous substance, do not lick or swallow. When the liquid is attaching to your hand, skin, cloth, etc., wash it thoroughly and immediately.
- Don't operate it above the absolute maximum rating.
- Don't disassemble the LCM.
- The operators should wear protections whenever he/she comes into contact with the module. Never touch any of the conductive parts such as the LSI pads, the copper leads on the PCB and the interface terminals with any parts of the human body.
- The modules should be kept in antistatic bags or other containers resistant to static for storage.
- The module is coated with a film to protect the display surface, be careful when peeling off this protective film since static electricity may be generated.

### 11.2 Storage

- Store it in an ambient temperature of  $25\pm 10^{\circ}\text{C}$ , and in a relative humidity of  $50\pm 10\%\text{RH}$ . Don't expose to sunlight or fluorescent light.
- Store it in a clean environment, free from dust, active gas, and solvent.
- Store it in anti-static electricity container.
- Store it without any physical load.

### 11.3 Soldering

- Use only soldering irons with proper grounding and no leakage.
- Iron: no higher than  $280\pm 10^{\circ}\text{C}$  and less than 3 sec during hand soldering.
- Rewiring: no more than 2 times.

## 12. Packing Method

No.	Item	Dimensions(mm)	Quantity	Remark
1	LCM Module	105.5*67.2*3.0	160PCS	
2	TRAY	344*285*85 (include 80pcs products/one pallet)	2PCS	
3	CARTON	385*315*227 (include 160pcs products/one carton)	1PCS	